PCN Number:	20200127000.1	**PCN Date:**	Feb. 18, 2020
Title:	Qualification of new Mold & Mount Compound for Select Devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	May 18, 2020	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new mount and mold compound for the devices in the Product Affected section below as follows:

Group 1 device:

	Current	New
Mount Compound	1400013111	1400160111
Mold Compound	18003331G1	180082310F

Group 2 device:

	Current	New
Mount Compound	1400013111	1400153112
Mold Compound	1800008131	18008231U1

Reason for Change:

Continuity of supply.
Current mount compound and mold compound material is no longer available.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

None

Product Affected: Group 1

LM97593VH/NOPB

Product Affected: Group 2

DP83848VYB/NOPB	DP83848YB/NOPB	DP83848YBX/NOPB

Qualification Report

Approve Date 16-Jan-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DP83848YB/NOPB	Qual Device: LM97593VH/NOPB
PC	Preconditioning	Level 3 - 245C	-	3/924/0
PC	Preconditioning	Level 3 - 260C	3/693/0	-
AC	Autoclave, 121C	96 Hours	3/231/0	3/231/0
BHAST	Biased HAST, 110C	264 Hours	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	3/231/0
TC	Temperature Cycle, -65C/150C	500 Cycles	3/224/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/90/0	3/90/0
SD	Solderability, Pb	Steam age, 8 Hours	3/66/0	3/66/0
SD	Solderability, Pb-Free	Steam age, 8 Hours	3/66/0	3/66/0
MQ	Manufacturability	Per mfg. site specification	3/Pass	3/Pass
DS	Die Shear	Die	3/30/0	3/30/0
PD	Physical Dimensions	Per mechanical drawing	3/15/0	3/15/0
LFA	Lead Finish Adhesion	Leads, min. 3 units	3/45/0	3/45/0
YLD	FTY and Bin Summary	-	3/Pass	3/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours
- The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com